S/N 09/259.849

AND TRADEMARK OF IN THE UNITED STATES PATERS

Applicant:

Paul A. Farrar

Serial No.:

09/259,849

Filed:

March 1, 1999

Title:

Examiner:

Group Art Unit:

Docket: 303.557US1

EGRATED CIRCUITS CONDUCTIVE STRUC

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant further request that a copy of the 1449 form, initialed by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Under 37 C.F.R. §1.97(b)(3), it is believed that no fee or certificate is required with this Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted.

PAUL A. FARRAR

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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(612) 371-2109

Date Movember 16, 1999

Reg. No. 35,635

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Assistant Commissioner of Patents, Washington, D.C. 20231 on November 4, 1999.

PATENT S/N 09/259,849

IN THE UNITED STATES PA ND TRADEMARK OFFICE

Applicant:

Paul A. Farrar

Serial No.:

09/259,849

Filed:

March 1, 1999

Title:

CONDUCTIVE STRUCT

Examiner:

Group Art Unit: 1765

Docket: 303.557US1

GRATED CIRCUITS

COMMUNICATION CONCERNING CO-PENDING APPLICATION(S)

Assistant Commissioner for Patents Washington, D.C. 20231

Applicant would like to bring to the Examiner's attention the following related copending application(s) in the above-identified patent application:

| Serial No. 09/032,197 | Filing Date 02/27/1998 | Attorney Docket 00303.459US1 | Title METHODS FOR MAKING COPPER AND OTHER METAL INTERCONNECTIONS IN INTEGRATED CIRCUITS |
|--------------------------|------------------------|---------------------------------|---|
| 09/128,859 | 08/04/1998 | 00303.473US1 | COPPER METALLURGY IN INTEGRATED CIRCUITS |
| 09/145,012 | 09/01/1998 | 00303.505US1 | INTEGRATED-CIRCUIT WITH OXIDATION-RESISTANT POLYMERIC LAYER |
| 09/256,123 | 02/24/1999 | 00303.505US2 | FORMING SUBMICRON INTEGRATED-CIRCUIT WIRING FROM GOLD, SILVER, COPPER AND OTHER METALS |

COMMUNICATION CONCERNING CO-PENDING APPLICATIONS

Serial Number: 09/259,849 Filing Date: March 1, 1999

Title: CONDUCTIVE STRUCTURES IN INTEGRATED CIRCUITS

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09/256,124

02/24/1999

00303.505US3

FORMING SUBMICRON
INTEGRATED-CIRCUIT WIRING FROM
GOLD, SILVER, COPPER AND OTHER
METALS

Respectfully submitted,

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Name